

HiPerFET™ Power MOSFETs Q-Class

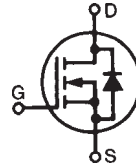
IXFH 17N80Q
IXFT 17N80Q

$V_{DSS} = 800\text{ V}$
 $I_{D25} = 17\text{ A}$
 $R_{DS(on)} = 0.60\ \Omega$

$t_{rr} \leq 250\text{ ns}$

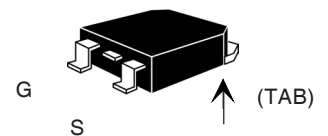
N-Channel Enhancement Mode
Avalanche Rated, High dv/dt, Low Q_g

Preliminary Data Sheet

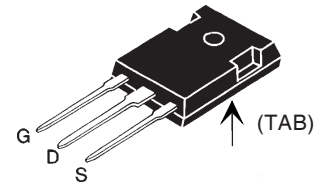


Symbol	Test Conditions	Maximum Ratings
V_{DSS}	$T_J = 25^\circ\text{C to } 150^\circ\text{C}$	800 V
V_{DGR}	$T_J = 25^\circ\text{C to } 150^\circ\text{C}; R_{GS} = 1\text{ M}\Omega$	800 V
V_{GS}	Continuous	± 20 V
V_{GSM}	Transient	± 30 V
I_{D25}	$T_C = 25^\circ\text{C}$	17 A
I_{DM}	$T_C = 25^\circ\text{C}$, pulse width limited by T_{JM}	68 A
I_{AR}	$T_C = 25^\circ\text{C}$	17 A
E_{AR}	$T_C = 25^\circ\text{C}$	30 mJ
E_{AS}	$T_C = 25^\circ\text{C}$	1.0 J
dv/dt	$I_S \leq I_{DM}$, $di/dt \leq 100\text{ A}/\mu\text{s}$, $V_{DD} \leq V_{DSS}$, $T_J \leq 150^\circ\text{C}$, $R_G = 2\ \Omega$	5 V/ns
P_D	$T_C = 25^\circ\text{C}$	400 W
T_J		-55 ... +150 °C
T_{JM}		150 °C
T_{stg}		-55 ... +150 °C
T_L	1.6 mm (0.062 in.) from case for 10 s	300 °C
M_d	Mounting torque	1.13/10 Nm/lb.in.
Weight	TO-247	6 g
	TO-268	4 g

TO-268 (D3) (IXFT) Case Style



TO-247 AD (IXFH)



G = Gate D = Drain
S = Source TAB = Drain

Symbol	Test Conditions ($T_J = 25^\circ\text{C}$, unless otherwise specified)	Characteristic Values		
		Min.	Typ.	Max.
V_{DSS}	$V_{GS} = 0\text{ V}$, $I_D = 3\text{ mA}$	800		V
$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 4\text{ mA}$	2.0		V
I_{GSS}	$V_{GS} = \pm 20\text{ V}_{DC}$, $V_{DS} = 0$			± 100 nA
I_{DSS}	$V_{DS} = V_{DSS}$, $T_J = 25^\circ\text{C}$			25 μA
	$V_{GS} = 0\text{ V}$, $T_J = 125^\circ\text{C}$			1 mA
$R_{DS(on)}$	$V_{GS} = 10\text{ V}$, $I_D = 0.5 I_{D25}$ Pulse test, $t \leq 300\ \mu\text{s}$, duty cycle $d \leq 2\%$			0.60 Ω

Features

- IXYS advanced low Q_g process
- International standard packages
- Low $R_{DS(on)}$
- Unclamped Inductive Switching (UIS) rated
- Fast switching
- Molding epoxies meet UL 94 V-0 flammability classification

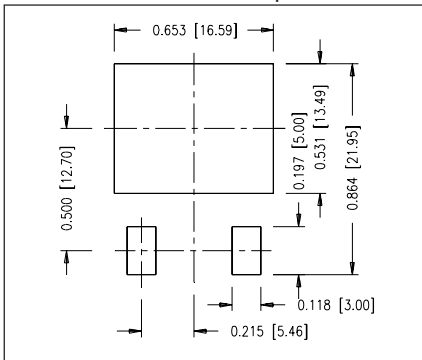
Advantages

- Easy to mount
- Space savings
- High power density

Symbol	Test Conditions	Characteristic Values		
		(T _J = 25°C, unless otherwise specified)		
		Min.	Typ.	Max.
g_{fs}	V _{DS} = 10 V; I _D = 0.5 I _{D25} , pulse test	9	17	S
C_{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		3600	pF
C_{oss}			350	pF
C_{rss}			100	pF
t_{d(on)}	V _{GS} = 10 V, V _{DS} = 0.5 V _{DSS} , I _D = 0.5 I _{D25} R _G = 1.5 Ω (External)		18	ns
t_r			27	ns
t_{d(off)}			53	ns
t_f			16	ns
Q_{g(on)}	V _{GS} = 10 V, V _{DS} = 0.5 V _{DSS} , I _D = 0.5 I _{D25}		95	nC
Q_{gs}			20	nC
Q_{gd}			40	nC
R_{thJC}	(TO-247)		0.31	K/W
R_{thCK}			0.25	K/W

Symbol	Test Conditions	Characteristic Values		
		(T _J = 25°C, unless otherwise specified)		
		min.	typ.	max.
I_S	V _{GS} = 0 V			15 A
I_{SM}	Repetitive;			60 A
V_{SD}	I _F = I _S , V _{GS} = 0 V, Pulse test, t ≤ 300 μs, duty cycle d ≤ 2 %			1.5 V
t_{rr}	I _F = I _S -di/dt = 100 A/μs, V _R = 100 V		0.85	250 ns
Q_{RM}				8 μC
I_{RM}				

Min Recommended Footprint

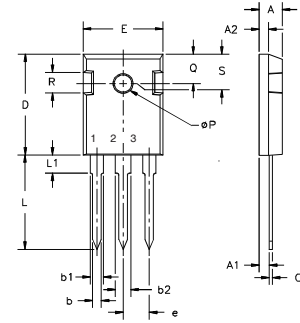


IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents:

4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715 6,306,728B1 6,259,123B1 6,306,728B1
4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025 6,404,065B1 6,162,665 6,534,343

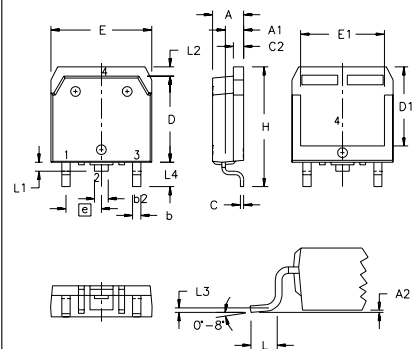
TO-247 AD Outline



Terminals: 1 - Gate 2 - Drain
3 - Source Tab - Drain

Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	4.7	5.3	.185	.209
A ₁	2.2	2.54	.087	.102
A ₂	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b ₁	1.65	2.13	.065	.084
b ₂	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L ₁		4.50		.177
ØP	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15	BSC	.242	BSC

TO-268 Outline



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.193	.201	4.90	5.10
A ₁	.106	.114	2.70	2.90
A ₂	.001	.010	0.02	0.25
b	.045	.057	1.15	1.45
b ₂	.075	.083	1.90	2.10
C	.016	.026	0.40	0.65
C ₂	.057	.063	1.45	1.60
D	.543	.551	13.80	14.00
D ₁	.488	.500	12.40	12.70
E	.624	.632	15.85	16.05
E ₁	.524	.535	13.30	13.60
e		.215 BSC		5.45 BSC
H	.736	.752	18.70	19.10
L	.094	.106	2.40	2.70
L ₁	.047	.055	1.20	1.40
L ₂	.039	.045	1.00	1.15
L ₃		.010 BSC		0.25 BSC
L ₄	.150	.161	3.80	4.10

Fig. 1. Output Characteristics
@ 25 Deg. C

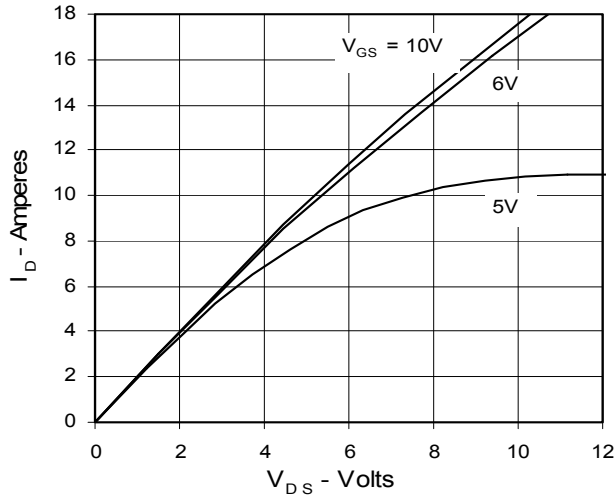


Fig. 2. Extended Output Characteristics
@ 25 deg. C

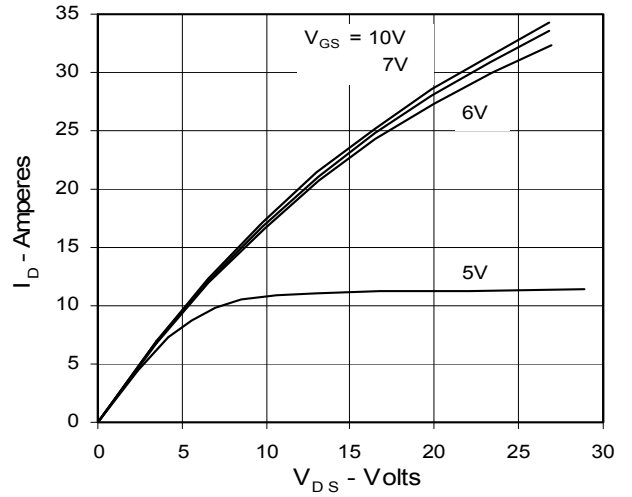


Fig. 3. Output Characteristics
@ 125 Deg. C

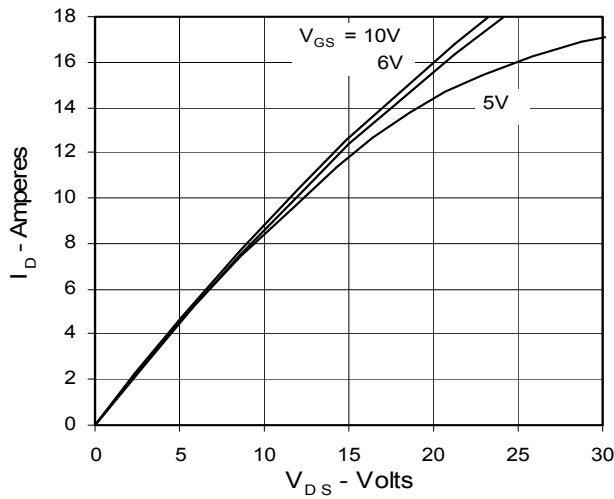


Fig. 4. $R_{DS(on)}$ Normalized to I_{D25} Value vs. Junction Temperature

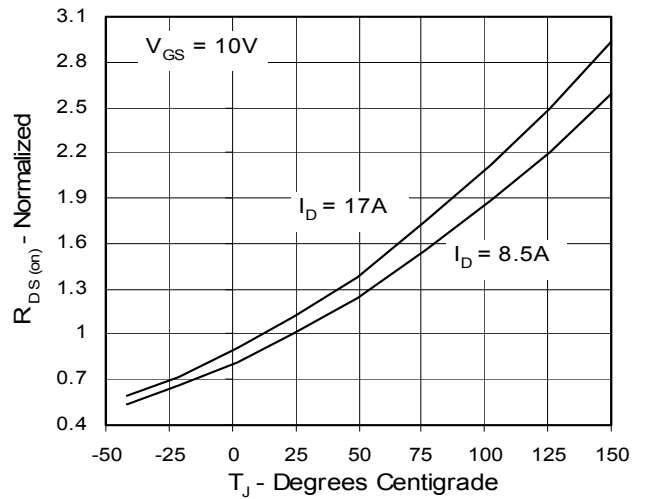


Fig. 5. $R_{DS(on)}$ Normalized to I_{D25} Value vs. I_D

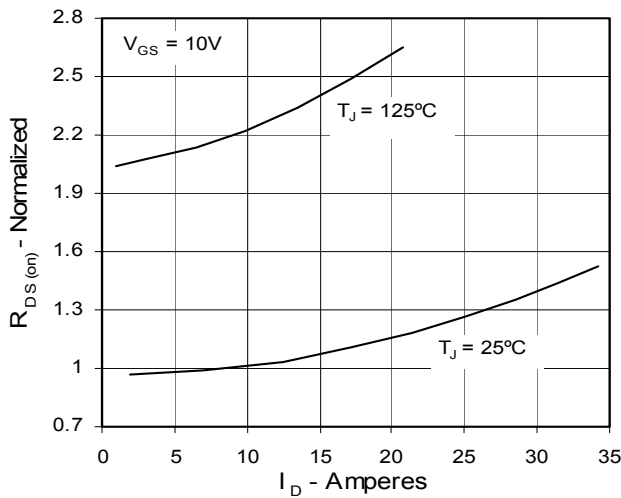


Fig. 6. Drain Current vs. Case Temperature

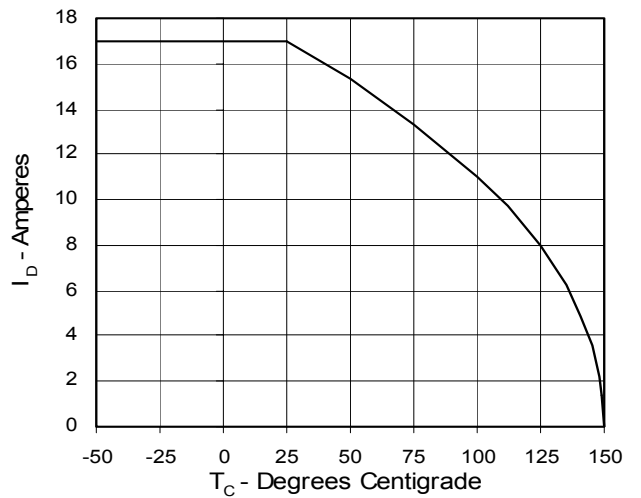


Fig. 7. Input Admittance

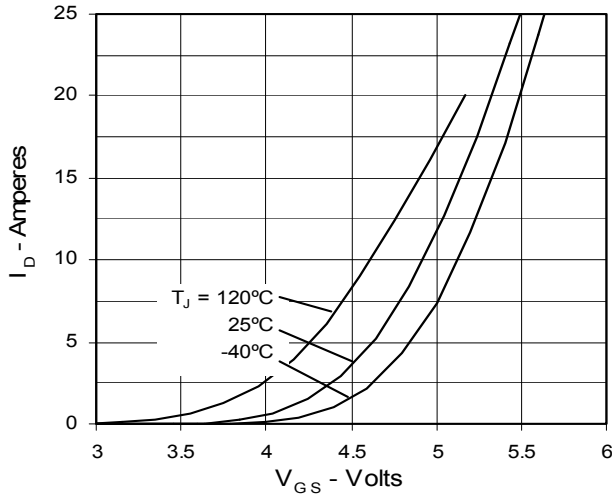


Fig. 8. Transconductance

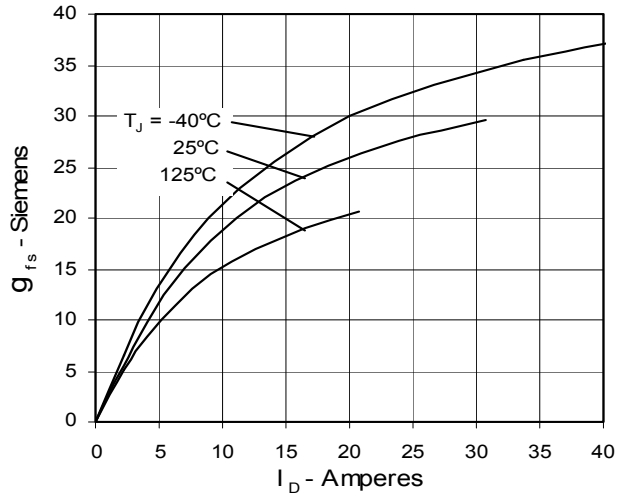


Fig. 9. Source Current vs. Source-To-Drain Voltage

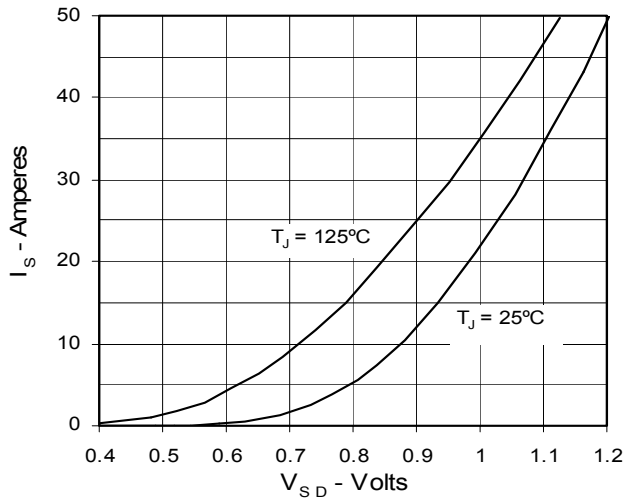


Fig. 10. Gate Charge

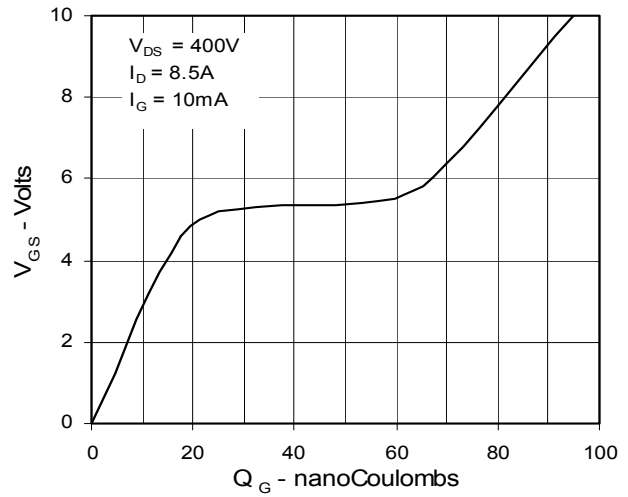


Fig. 11. Capacitance

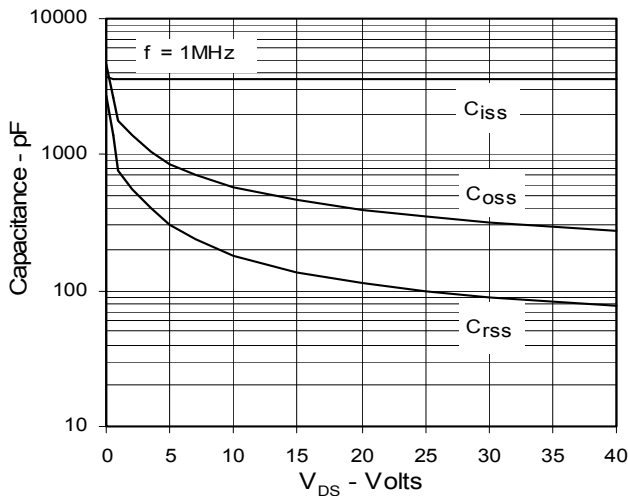
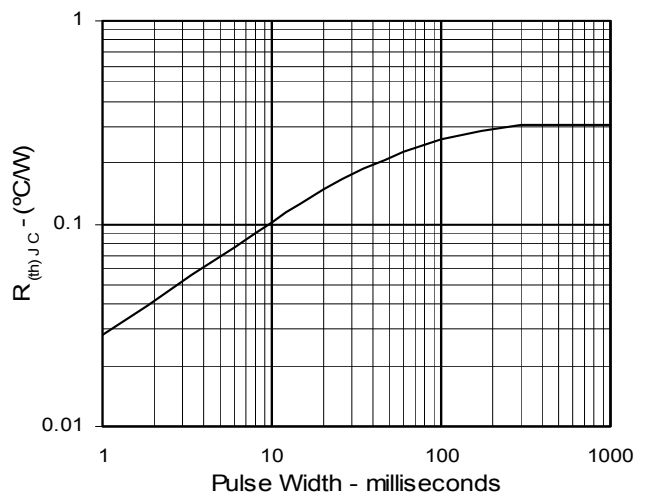


Fig. 12. Maximum Transient Thermal Resistance



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